- Qualified for Automotive Applications
- Wide Analog Input Voltage Range: ±5 V Max
- Low ON Resistance
 - 70 Ω Typical (V_{CC} V_{EE} = 4.5 V)
 - 40 Ω Typical (V_{CC} V_{EE} = 9 V)
- Low Crosstalk Between Switches
- Fast Switching and Propagation Speeds
- Break-Before-Make Switching
- Wide Operating Temperature Range: -40°C to 125°C

description/ordering information

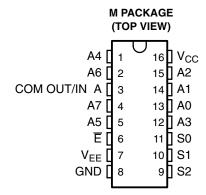
This device is a digitally controlled analog switch that utilizes silicon-gate CMOS technology to achieve operating speeds similar to LSTTL, with the low power consumption of standard CMOS integrated circuits.

Operation Control Voltage: 4.5 V to 5.5 V

Switch Voltage: 0 V to 10 V

Direct LSTTL Input Logic Compatibility:
 V_{IL} = 0.8 V Max, V_{IH} = 2 V Min

• CMOS Input Compatibility: $I_I \le 1 \mu A$ at V_{OL} , V_{OH}



This analog multiplexer/demultiplexer controls analog voltages that may vary across the voltage supply range (i.e., V_{CC} to V_{EE}). It is a bidirectional switch that allows any analog input to be used as an output and vice-versa. The switch has low ON resistance and low OFF leakages. In addition, this device has an enable control that, when high, disables all switches to their OFF state.

ORDERING INFORMATION[†]

TA	PACKAGE [‡]		ORDERABLE PART NUMBER [§]	TOP-SIDE MARKING
-40°C to 125°C	SOIC - M	Reel of 2500	CD74HCT4051QM96Q1	HCT4051Q

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

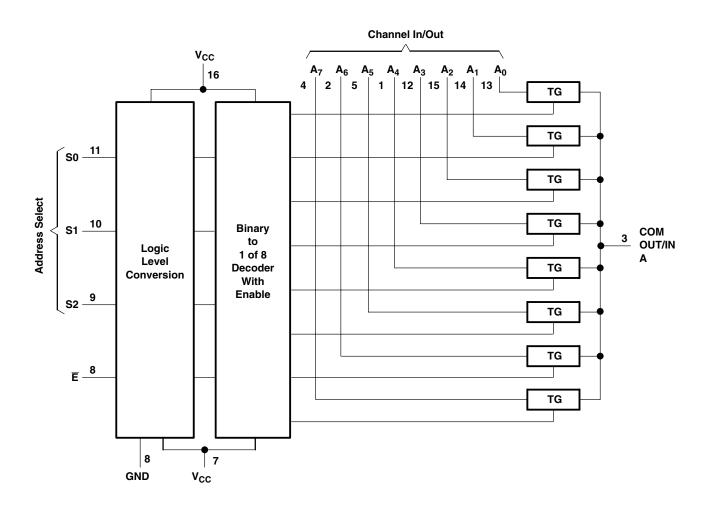
[§] The suffix 96 denotes tape and reel.

FUNCTION TABLE

	INPU	011 011 1111 111		
ENABLE	S2	S1	S0	ON CHANNELS
L	L	L	L	A0
L	L	L	Н	A1
L	L	Н	L	A2
L	L	Н	Н	A3
L	Н	L	L	A4
L	Н	L	Н	A5
L	Н	Н	L	A6
L	Н	Н	Н	A7
Н	Χ	Χ	Χ	None

X = Don't care

logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range: V _{CC} – V _{EE} (see Note 1)	
V _{CC}	0.5 V to +7 V
V _{EE}	0.5 V to –7 V
Input clamp current, I_{IK} ($V_I < -0.5 \text{ V or } V_I > V_{CC} + 0.5 \text{ V}$)	±20 mA
Output clamp current, I_{OK} ($V_O < V_{EE} - 0.5 \text{ V or } V_O > V_{CC} + 0.5 \text{ V}$)	±20 mA
Switch current ($V_I > V_{EE} - 0.5 \text{ V}$ or $V_I < V_{CC} + 0.5 \text{ V}$)	±25 mA
Continuous current through V _{CC} or GND	±50 mA
V _{EE} current, I _{EE}	–20 mA
Package thermal impedance, θ_{JA} (see Note 2)	73°C/W
Maximum junction temperature, T _J	150°C
Lead temperature (during soldering):	
At distance $1/16 \pm 1/32$ inch $(1,59 \pm 0,79$ mm) from case for 10 s max	300°C
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages referenced to GND unless otherwise specified.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

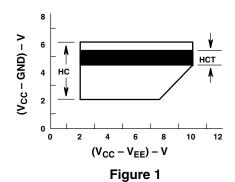
		MIN	MAX	UNIT
V_{CC}	Supply voltage	4.5	5.5	V
	Supply voltage, V _{CC} – V _{EE} (see Figure 1)	2	10	٧
V_{EE}	Supply voltage (see Note 4 and Figure 2)	0	-6	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		8.0	V
V_{I}	Input control voltage	0	V_{CC}	V
V_{IS}	Analog switch I/O voltage	V _{EE}	V_{CC}	V
t _t	Input transition (rise and fall) time $V_{CC} = 4.5 \text{ V}$	0	500	ns
T_A	Operating free-air temperature	-40	125	°C

NOTES: 3. All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

4. In certain applications, the external load resistor current may include both V_{CC} and signal-line components. To avoid drawing V_{CC} current when switch current flows into the transmission gate inputs, the voltage drop across the bidirectional switch must not exceed 0.6 V (calculated from r_{on} values shown in electrical characteristics table). No V_{CC} current flows through R_L if the switch current flows into the COM OUT/IN A terminal.



recommended operating area as a function of supply voltages



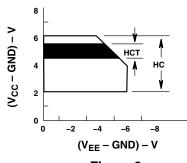


Figure 2

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST COM	V _{EE}	V _{CC}	T,	ղ = 25°C	;	T _A = -		UNIT	
					MIN	TYP	MAX	MIN	MAX	
		W WW	0 V	4.5 V		70	160		240	
_	$I_0 = 1 \text{ mA},$	$V_{IS} = V_{CC}$ or V_{EE}	-4.5 V	4.5 V		40	120		180	
r _{on}	V _I = V _{IH} or V _{IL} , See Figure 9	., ., .,	0 V	4.5 V		90	180		270	Ω
		$V_{IS} = V_{CC}$ to V_{EE}	-4.5 V	4.5 V		45	130		195	
						10				
$\Delta r_{\sf on}$	Between any two char	-4.5 V	4.5 V		5				Ω	
l.	For switch OFF: When V _{IS} = V _{CC} , V _{OS} When V _{IS} = V _{EE} , V _{OS} For switch ON:	0 V	6 V			±0.2		±2	^	
l _{IZ}	All applicable combinate voltage levels, $V_I = V_{IH}$ or V_{IL}	-5 V	5 V			±0.4		±4	μА	
I _{IL}	$V_I = V_{CC}$ or GND	Control input		5.5 V			±0.1		±1	μΑ
	l _O = 0,	When $V_{IS} = V_{EE}$, $V_{OS} = V_{CC}$	0 V	5.5 V			8		160	4
Icc	$V_I = V_{CC}$ or GND	-4.5 V	5.5 V			16		320	μΑ	
Δl _{CC}	Per input pin: 1 unit los See Note 5, V _{IN} = V _{CO}		4.5 V to 5.5 V		100	360		490	μА	

NOTE 5: For dual-supply systems, theoretical worst case ($V_1 = 2.4 \text{ V}$, $V_{CC} = 5.5 \text{ V}$) specification is 1.8 mA.

HCT input loading

TYPE	INPUT	UNIT LOADS†
4051	All	0.5

 $^{^{\}dagger}$ Unit load is ΔI_{CC} limit specified in the electrical characteristics table, e.g., 360 μA max at 25°C.



switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 8)

PARAMETER	FROM	TO	LOAD CAPACITANCE	VEE	V _{CC}	T,	գ = 25°C	;	T _A = -		UNIT	
	(INPUT)	(OUTPUT)	CAPACITANCE			MIN	TYP	MAX	MIN	MAX		
			C _L = 15 pF		5 V		4					
t _{pd}	IN	OUT	C _L = 50 pF	0 V	4.5 V			12		18	ns	
			C _L = 50 pF	-4.5 V	4.5 V			8		12		
			C _L = 15 pF		5 V		23					
t _{en}	S or \overline{E}	OUT	C _L = 50 pF	0 V	4.5 V			55		83	ns	
			C _L = 50 pF	-4.5 V	4.5 V			39		59		
			C _L = 15 pF		5 V		19					
t _{dis}	S or E	OUT	C _L = 50 pF	0 V	4.5 V			45		68	ns	
			C _L = 50 pF	-4.5 V	4.5 V			32		48		
C _I	Control							10		10	pF	

operating characteristics, V_{CC} = 5 V, T_A = 25°C, input t_r , t_f = 6 ns

	PARAMETER				
C_{pd}	Power dissipation capacitance (see Note 6)	52	pF		

NOTE 6: C_{pd} is used to determine the dynamic power consumption (P_D), per package.

 $\begin{aligned} P_{D}^{pd} &= (C_{pd} \times V_{CC}^2 \times f_I) + \Sigma (C_L + C_S) \ V_{CC}^2 \times f_O \\ f_O &= \text{output frequency} \end{aligned}$

f_I = input frequency

C_L = output load capacitance

 C_S = switch capacitance

V_{CC} = supply voltage

analog channel characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{EE}	V _{CC}	TYP	UNIT
CI	Switch input capacitance				5	pF
ССОМ	Common output capacitance				25	pF
	Minimum switch frequency	See Figure 3 and Figure 10 and	–2.25 V	2.25 V	145	NAL I-
^T max	response at -3 dB	Notes 7 and 8		4.5 V	180	MHz
	Otro a consequent distantia a	Over Filmone F	-2.25 V	2.25 V	0.035	0/
	Sine-wave distortion	See Figure 5	-4.5 V	4.5 V	0.018	%
	E or address select (S0, S1, S2) to	One Figure 0 and Nation 0 and 0	-2.25 V	2.25 V	TBE	
	switch feedthrough noise	See Figure 6 and Notes 8 and 9	-4.5 V	4.5 V	TBE	mV
	Cuitab OFF signal to adthrough	See Figure 7 and Figure 11 and	-2.25 V	2.25 V	-73	٩D
	Switch OFF signal feedthrough	Notes 8 and 9	-4.5 V	4.5 V	-75	dB

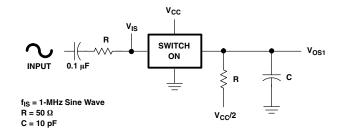
NOTES: 7. Adjust input voltage to obtain 0 dBm at V_{OS} for f_{IN} = 1 MHz.

8. V_{IS} is centered at $(V_{CC} - V_{EE})/2$.

9. Adjust input for 0 dBm.



PARAMETER MEASUREMENT INFORMATION



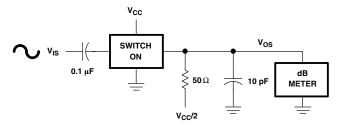


Figure 3. Frequency-Response Test Circuit

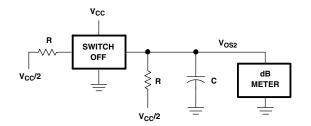


Figure 4. Crosstalk Between Two Switches Test Circuit

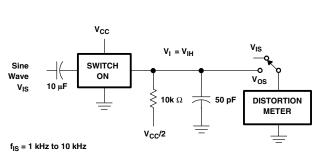


Figure 5. Sine-Wave Distortion Test Circuit

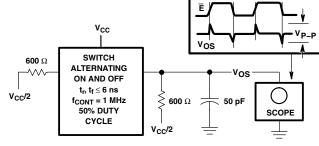


Figure 6. Control-to-Switch Feedthrough Noise Test Circuit

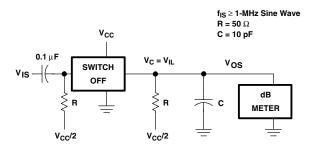
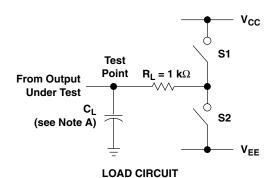


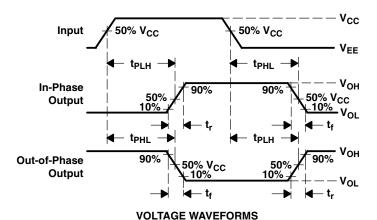
Figure 7. Switch OFF Signal Feedthrough Test Circuit

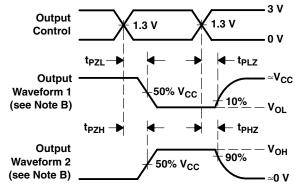


PARAMETER MEASUREMENT INFORMATION



PARAI	METER	S1	S2		
	t _{PZH}	Open	Closed		
t _{en}	t _{PZL}	Closed Open Open Closed			
•	t _{PHZ}	Open	Closed		
t _{dis}	t _{PLZ}	Closed	Closed Open Closed		
t _{pd}	·	Open	Open		





PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
OUTPUT ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50~\Omega$, $t_r = 6~ns$, $t_f = 6~ns$.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time, with one input transition per measurement.
- F. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- G. t_{PZL} and t_{PZH} are the same as t_{en} .
- H. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 8. Load Circuit and Voltage Waveforms



TYPICAL CHARACTERISTICS

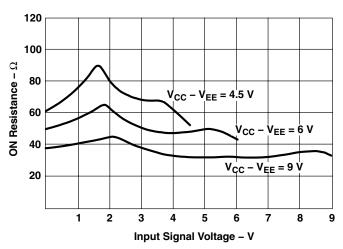


Figure 9. Typical ON Resistance vs Input Signal Voltage

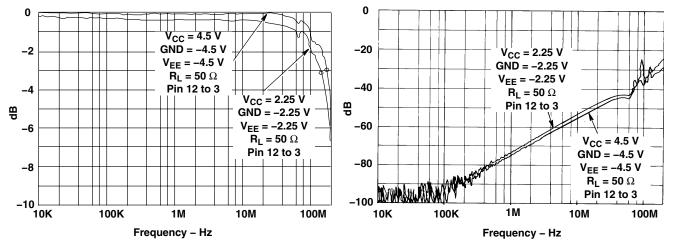


Figure 10. Channel ON Bandwidth

Figure 11. Channel OFF Feedthrough





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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HCT4051QM96Q1	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HCT4051Q	Samples
D24051QM96G4Q1	LIFEBUY	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HCT4051Q	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF CD74HCT4051-Q1:

● Catalog : CD74HCT4051

Military : CD54HCT4051

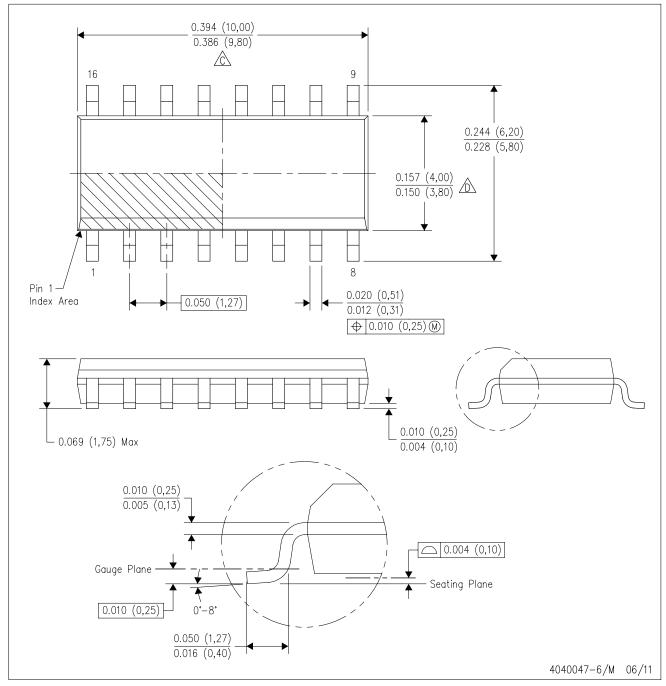
NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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